

Product / Package Information

Package	TSOT
Body Size/Pitch	
Lead Count	8
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic material:	Silica	60676-86-0	5.18 E-03	87.3	873000	38.23	382255
Thermosets	Phenol Resin	Proprietary	2.67 E-04	4.5	45000	1.97	19704
Thermosets	Epoxy Resin 1	Proprietary	1.78 E-04	3.0	30000	1.31	13136
Thermosets	Epoxy Resin 2	Proprietary	1.78 E-04	3.0	30000	1.31	13136
Others	Others	Proprietary	1.19 E-04	2.0	20000	0.88	8757
Other inorganic material:	Carbon Black	1333-86-4	1.19 E-05	0.2	2000	0.09	876
Subtotal			5.93 E-03	100.0	1000000	44	437864

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.55 E-03	97.5	975000	40.98	409819
Copper & its alloys	Iron	7439-89-6	1.34 E-04	2.35	23500	0.99	9878
Copper & its alloys	Zinc	7440-66-6	6.83 E-06	0.12	1200	0.05	504
Copper & its alloys	Phosphorus	7723-14-0	1.71 E-06	0.03	300	0.01	126
Subtotal			5.69 E-03	100	1000000	42	420327

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.75 E-05	100	1000000	0.42	4246

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	6.13 E-04	100	1000000	4.53	45265

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.00 E-05	99.99	1000000	0.15	1477

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic material:	Doped Silicon	7440-21-3	1.16 E-03	100	1000000	8.57	85653

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.64 E-05	80.50	805000	0.42	4161
Other organic material:	Carbocyclic Acrylates	Proprietary	7.00 E-06	10.00	100000	0.05	517
Other organic material:	Bismaleimide resin	Proprietary	2.10 E-06	3.00	30000	0.02	155
Other organic material:	2-preponic acid, 2-methyl	68586-19-6	2.10 E-06	3.0	30000	0.02	155
Others	Additive	Proprietary	2.10 E-06	3.0	30000	0.02	155
Other organic material:	Dicumyl peroxide	80-43-3	3.50 E-07	0.5	5000	0.00	26
Subtotal			7.00 E-05	100.00	1000000	0.52	5169

Package Totals	Weight (g)	Percentage (%)	PPM
	1.35 E-02	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability any inaccuracy of such information



ADI Proprietary

Product / Package Information

Package	TSOT - COL
Body Size/Pitch	
LeadCount	8
Option	NiPdAu

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.18 E-03	87.3	873000	40.04	400378
Thermosets	Phenol Resin	Proprietary	2.67 E-04	4.5	45000	2.06	20638
Thermosets	Epoxy Resin 1	Proprietary	1.78 E-04	3.0	30000	1.38	13759
Thermosets	Epoxy Resin 2	Proprietary	1.78 E-04	3.0	30000	1.38	13759
Others	Others	Proprietary	1.19 E-04	2.0	20000	0.92	9172
Other inorganic materials	Carbon Black	1333-86-4	1.19 E-05	0.2	2000	0.09	917
Subtotal			5.93 E-03	100.0	1000000	46	458623

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.54 E-03	97.5	975000	42.81	428100
Copper & its alloys	Iron	7439-89-6	1.33 E-04	2.35	23500	1.03	10318
Copper & its alloys	Zinc	7440-66-6	6.81 E-06	0.12	1200	0.05	527
Copper & its alloys	Phosphorus	7723-14-0	1.70 E-06	0.03	300	0.01	132
Subtotal			5.68 E-03	100	1000000	44	439077

Internal/External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	6.61 E-05	90.91	909091	0.51	5114
Precious metals	Palladium	7440-05-3	5.75 E-06	7.91	79051	0.04	445
Precious metals	Gold	7440-57-5	8.63 E-07	1.19	11858	0.01	67
Subtotal			7.27 E-05	100.00	1000000	0.56	5625

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.00 E-05	99.99	1000000	0.15	1547

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.16 E-03	100	1000000	8.97	89714

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Aluminum oxide	1344-28-1	2.45 E-05	35	350000	0.19	1895
Other organic materials	Diethylene glycol monoethyl ether acetate	112-15-1	2.45 E-05	35	350000	0.19	1895
Thermoset	Epoxy Resin	Proprietary	1.75 E-05	25	250000	0.14	1353
Others	Amine	Proprietary	3.50 E-06	5	50000	0.03	271
Subtotal			7.00 E-05	100	1000000	0.54	5414

Package Totals			Weight (g) 1.29 E-02			Percentage (%) 100	PPM 1000000
-----------------------	--	--	--------------------------------	--	--	------------------------------	-----------------------

Note: The information provided in this declaration are true to the best of ADI's knowledge ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability any inaccuracy of such information.



ADI Proprietary

Product / Package Information

Package	TSOT
Body Size	
LeadCount	8
Terminal Finish	85Sn15Pb

Environmental Compliance Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	4.63 E-03	78.00	780000	34.05		340495
Thermosets	Solid epoxy resin	Proprietary	7.12 E-04	12.00	120000	5.24		52384
Thermosets	Phenol resin	Proprietary	3.56 E-04	6.00	60000	2.62		26192
Other organic materials	Brominated epoxy	Proprietary	1.19 E-04	2.00	20000	0.87		8731
Other inorganic materials	Antimony Trioxide	1309-64-4	1.07 E-04	1.80	18000	0.79		7858
Other inorganic materials	Carbon Black	1333-86-4	1.19 E-05	0.20	2000	0.09		873
Subtotal			5.93 E-03	100.0	1000000	43.65		436532

Leadframe								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	5.55 E-03	97.50	975000	40.85		408531
Copper & its alloys	Iron	7439-89-6	1.34 E-04	2.35	23500	0.98		9847
Copper & its alloys	Zinc	7440-66-6	6.83 E-06	0.12	1200	0.05		503
Copper & its alloys	Phosphorus	7723-14-0	1.71 E-06	0.03	300	0.01		126
Subtotal			5.69 E-03	100.00	1000000	41.90		419006

Internal Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	5.75 E-05	100.0	1000000	0.42		4233

External Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	5.57 E-04	85.0	85000	4.10		40931
Tin & its alloys	Lead	7439-92-1	9.82 E-05	15.0	150000	0.72		7232
Subtotal			6.55 E-04	100.0	1000000	4.82		48212

Bond Wires								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-67-5	2.00 E-05	99.99	1000000	0.15		1472

Chip								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	1.16 E-03	100.0	1000000	8.54		85392

Die Attach								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	5.60 E-05	80	800000	0.41		4122
Thermosets	Epoxy Resin	Proprietary	1.05 E-05	15	150000	0.08		773
Others	Curing agent & hardener	Proprietary	3.50 E-06	5	50000	0.03		258
Subtotal			7.00 E-05	100	1000000	0.52		5153

Package Totals	Weight (g)	Percentage (%)	PPM
	1.36 E-02	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability
 any inaccuracy of such information.



ADI Proprietary